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December 11, 2002  
Date

Stephanie Jansen  
Stephanie Jansen

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant	: Tongbi Jiang	Attorney Docket No.:	500182.01 (660073.774)
Serial No.	: 09/365,356	Group Art Unit	: 2813
Filed	: July 30, 1999	Examiner	: Nema O. Berezny
Title	: METHOD AND STRUCTURE FOR MANUFACTURING IMPROVED YIELD SEMICONDUCTOR PACKAGED DEVICES		

**PRELIMINARY AMENDMENT**

Box RCE  
Commissioner of Patents  
Washington, D.C. 20231

Sir:

Please amend the above-identified application as follows:

In the Claims:

Please amend claims 1, 11, 38 and 42 as follows:

- H1/2/3/4/5*
1. (Four Times Amended) A semiconductor device package, comprising:  
a semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated, the die having first and second pairs of opposed lateral edges;  
at least one electrically conductive external terminal;  
an interposer having a die attach surface and an external surface opposite of the die attach surface disposed in between the semiconductor die and the at least one external